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(12) **United States Design Patent** (10) **Patent No.:** **US D844,577 S**
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(54) **CONDUCTOR PAD**

(56) **References Cited**

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(**) Term: **15 Years**

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Related U.S. Application Data

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/133, 182; 324/754.01, 754.02, 324/754.03; 361/19, 107, 637, 515, 813; 439/43, 52, 66, 12, 208, 210, 456, 457, 439/458, 902; 438/614, 610, 584, 612, 438/618

CPC ... H01L 24/03; H01L 24/05; H01L 23/49575; H01L 24/34; H01L 2224/05556; H01J 37/08; H01J 37/26; G01N 23/00

See application file for complete search history.

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(57) **CLAIM**

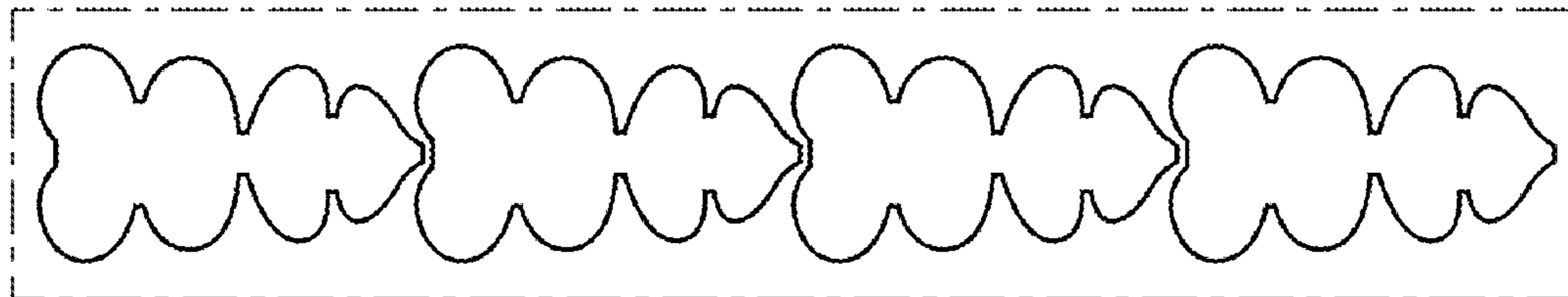
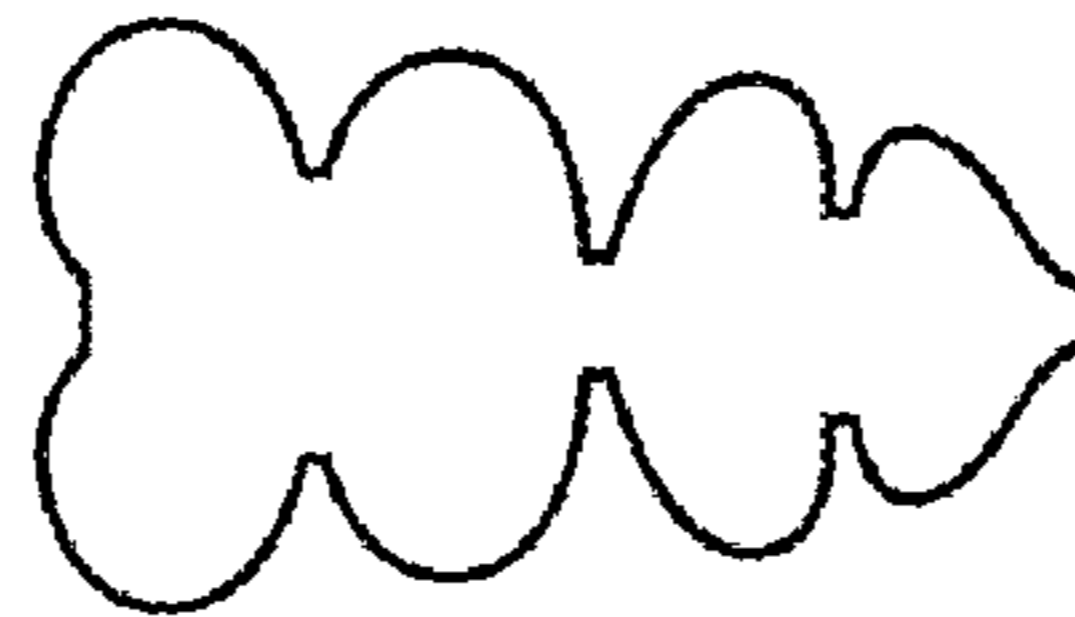
The ornamental design for a conductor pad, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a first embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof; and, FIG. 2 is a top plan view of a second embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.

All surfaces not shown form no part of the claimed design.

1 Claim, 1 Drawing Sheet



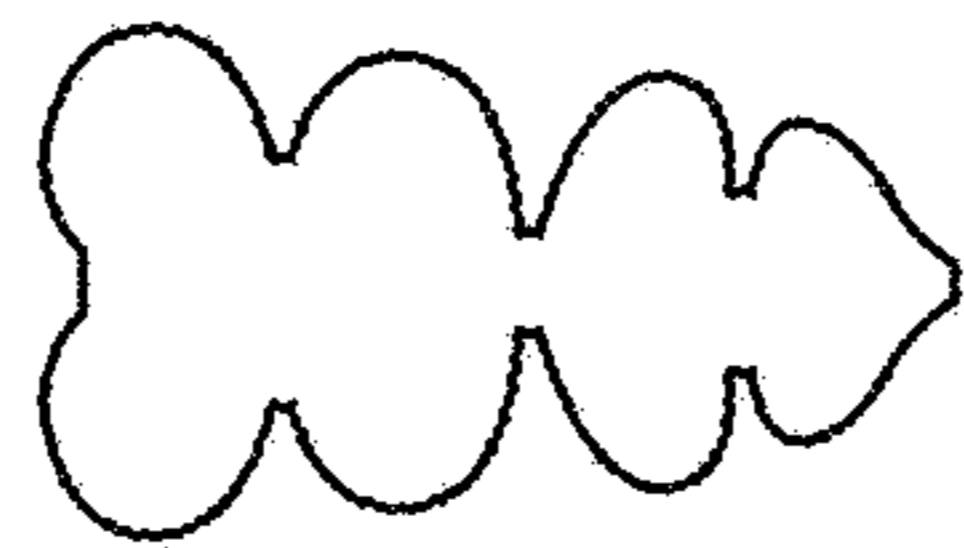


FIG. 1

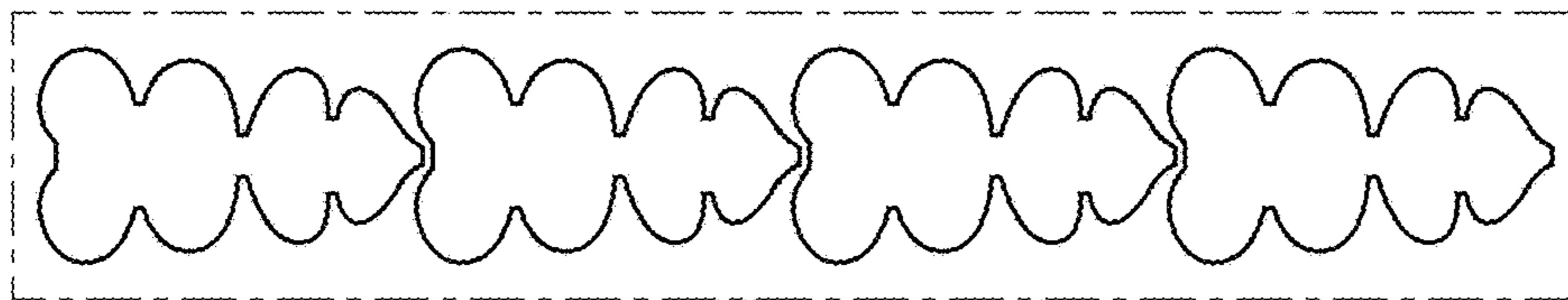


FIG. 2